

Strasbaugh 6DS-SP Production CMP System



Your source for leading-edge surface processing solutions



The Strasbaugh 6DS-SP CMP System is a robust and reliable CMP platform delivering low-cost, high-yield processes for 100mm to 200mm diameter material.

OPTIONS AVAILABLE

Various styles of multi-zone membrane wafer carriers for improved uniformity and edge control performance
End Point Determination (EPD) system
Wafer size conversion kits
Slurry blending and distribution system
Temperature control of primary polishing platen
Secondary platen pad conditioning system
Vacuum system with automatic fluid separation unit
Curtain rinse between polishing platens to reduce slurry cross-contamination

FEATURES

- Membrane wafer carriers for improved process performance
- Dual polishing platens for one or two-step processes
- Dual polishing spindles for 100-200mm wafers and higher throughput
- Proven process performance for dielectrics, metals, poly, and STI
- Pad conditioning system provides in-situ programmable selective pad conditioning with 20 zones of programmable control
- Four cassette elevators, with robotic load/unload system
- Hydrolift load station provides better reliability and improved cleanliness

